



PATENT
790001-2034

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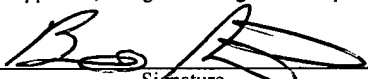
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Noriaki Matsunaga et al.
Serial No. : 10/628,689
Filed : July 28, 2003
For : ***SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD***
Examiner : Hoai V. Pham
Art Unit : 2814

745 Fifth Avenue
New York, NY 10151

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: **Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450**, on **December 22, 2004**.

Bruno Polito, Reg. No. 38,580
(Name of Applicant, Assignee or Registered Representative)


Signature

December 22, 2004
Date of Signature

AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed September 22, 2004, please amend the above-identified application as follows.

IN THE TITLE

Please change the title to:

--Semiconductor Device Having Wiring Layer Formed in Wiring Groove--.